

Atty. Docket No. PIA31220/DBE/US

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

:

Byoung Young KANG

: GROUP ART UNIT:

SERIAL NO: NEW APPLICATION

:

FILED: HEREWITH

: EXAMINER:

FOR: Ceramic Packaging Method Employing Flip-Chip Bonding

I hereby certify that this document is being deposited with the United States Postal Service as Express Mail No. EU190172534US in an envelope addressed to Commissioner for Patents, Washington, D.C. 20231, on December 30, 2003.

By:


Jennie Heaton

REQUEST FOR PRIORITY UNDER 35 U.S.C. 119(a)-(b) AND 37 C.F.R. 1.55

COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Applicant respectfully requests under the Paris Convention for the Protection of Intellectual Property the benefit of the filing date of the prior foreign application(s) identified below:

<u>Serial No.</u>	<u>Filing Date</u>	<u>Country of Filing</u>
10-2002-0086653	December 30, 2002	Republic of KOREA

A certified copy of the priority application will be filed before any U.S. patent issues from the above-captioned application.

Respectfully submitted,



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